



## TA-08

### Temporary Adhesive

#### Features:

- 100% Volatilization
- Adhesive for Semi-Conductor Components
- Zero Dry-Out
- No Post-Reflow Residues
- Soluble in Isopropyl Alcohol

#### Description:

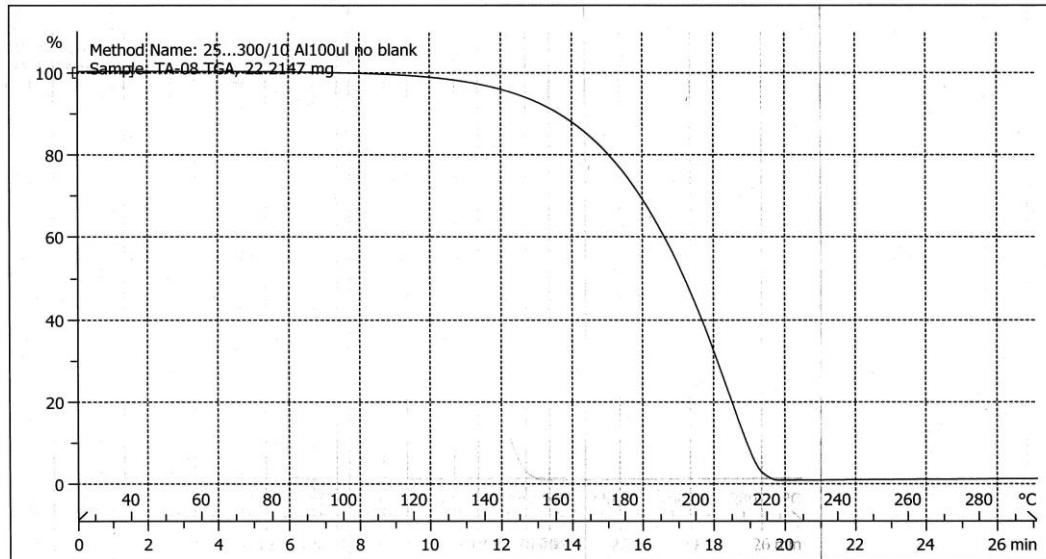
TA-08 temporary adhesive is designed to hold components in place during fluxed atmosphere reflow eliminating the need for solder paste. TA-08 adhesive provides good adhesion to a wide variety of components. TA-08 adhesive is used for temporary adhesion of bumped components during fluxed atmosphere reflow. After reflow, there is no residue to inhibit wire bonding or poison semi-conductor preform.

#### Application:

- TA-08 is designed for printing and dispensing.
- Adhesive dispense quality depends upon dispense pressure, time, nozzle size, and temperature.
- TA-08 is delivered ready to use, and are available in syringes, cartridges, and jars.

#### Base Reflow Profile on TGA:

### TA-08 TGA



#### Cleaning:

- Adhesive may be removed from the PCB with Isopropyl Alcohol.

#### Handling and Storage:

- This product should be stored at room temperature (25°C-78°F)
- Shelf life of 1 year when stored properly at room temperature.
- Keep container sealed when not in use.

**Safety:**

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

**Physical Properties:**

Parameter	Value
Visual	TA-08 (waxy, pasty material)
Color	Clear
Tack Force	TA-08: >100gf
Viscosity	31000/17000 cps @ 20°C
Density	0.99/0.99 g/cubic cm

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Asia-Pacific +86-755-2993-6487 · India +91-80-41554753 · [info@aimsolder.com](mailto:info@aimsolder.com) · [www.aimsolder.com](http://www.aimsolder.com)  
AIM is ISO9001:2008 CERTIFIED

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